INTEGRATED CIRCUITS

DATA SHEET

74LV245Octal bus transceiver (3-State)

Product specification Supersedes data of 1997 Feb 19 IC24 Data Handbook





Philips Semiconductors Product specification

Octal bus transceiver (3-State)

74LV245

FEATURES

• Wide operating voltage: 1.0 to 5.5 V

Optimized for low voltage applications: 1.0 to 3.6 V

Accepts TTL input levels between V_{CC} = 2.7 V and V_{CC} = 3.6 V

 Typical V_{OLP} (output ground bounce) < 0.8 V at V_{CC} = 3.3 V, $T_{amb} = 25^{\circ}C$

 Typical V_{OHV} (output V_{OH} undershoot) > 2 V at V_{CC} = 3.3 V, $T_{amb} = 25^{\circ}C$

Output capability: bus driver

I_{CC} category: MSI

DESCRIPTION

The 74LV245 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT245.

The 74LV245 is an octal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. The 74LV245 features an output enable (OE) input for easy cascading and a send/receive (DIR) input for direction control. OE controls the outputs so that the buses are effectively isolated.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay A _n to B _n ; B _n to A _n	$C_L = 15 \text{ pF};$ $V_{CC} = 3.3 \text{ V}$	7.0	ns
C _I	Input capacitance		3.5	pF
C _{I/O}	Input/output capacitance		10	pF
C _{PD}	Power dissipation capacitance per buffer	$V_{CC} = 3.3 \text{ V}$ V _I = GND to V _{CC} , note 1	40	pF

NOTE:

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

 $\begin{aligned} &f_i = \text{input frequency in MHz; } C_L = \text{output load capacitance in pF;} \\ &f_o = \text{output frequency in MHz; } V_{CC} = \text{supply voltage in V;} \end{aligned}$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #	
20-Pin Plastic DIL	-40°C to +125°C	74LV245 N	74LV245 N	SOT146-1	
20-Pin Plastic SO	-40°C to +125°C	74LV245 D	74LV245 D	SOT163-1	
20-Pin Plastic SSOP Type II	–40°C to +125°C	74LV245 DB	74LV245 DB	SOT339-1	
20-Pin Plastic TSSOP Type I	-40°C to +125°C	74LV245 PW	74LV245PW DH	SOT360-1	

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION				
1	DIR	Direction				
2, 3, 4, 5, 6, 7, 8, 9	A ₀ to A ₇	Data inputs/outputs				
10	GND	Ground (0 V)				
18, 17, 16, 15, 14, 13, 12, 11	B ₀ to B ₇	Data inputs/outputs				
19	ŌĒ	Output enable input (active LOW)				
20	V _{CC}	Positive supply voltage				

FUNCTION TABLE

INP	UTS	INPUTS/	OUTPUT
ŌĒ	DIR	A _n	B _n
L	L	A = B	Inputs
L	Н	Inputs	B = A
Н	Х	Z	Z

NOTES:

HIGH voltage level LOW voltage level

don't care

X Z high impedance OFF-state

^{1.} C_{PD} is used to determine the dynamic power dissipation (P_D in μW)

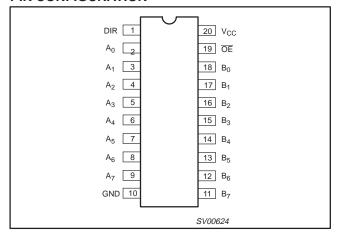
 $[\]sum$ (C_L × V_{CC}² × f_o) = sum of the outputs.

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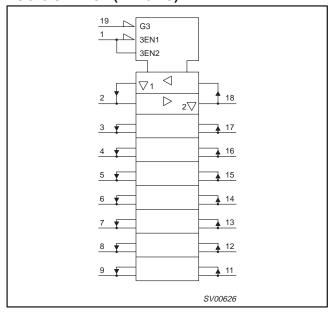
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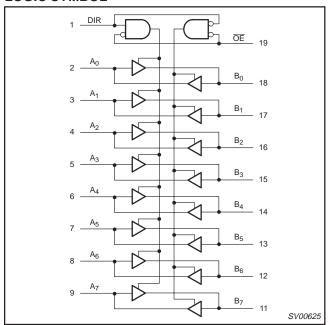
PIN CONFIGURATION



LOGIC SYMBOL (IEEE/IEC)



LOGIC SYMBOL



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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
V _{CC}	DC supply voltage	See Note 1	1.0	3.3	5.5	V
VI	Input voltage		0	_	V _{CC}	V
Vo	Output voltage		0	_	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.0V \text{ to } 2.0V \\ V_{CC} = 2.0V \text{ to } 2.7V \\ V_{CC} = 2.7V \text{ to } 3.6V \\ V_{CC} = 3.6V \text{ to } 5.5V$	 - -	- - -	500 200 100 50	ns/V

ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
± I _{IK}	DC input diode current	$V_{I} < -0.5 \text{ or } V_{I} > V_{CC} + 0.5V$	20	mA
± I _{OK}	DC output diode current	$V_{O} < -0.5 \text{ or } V_{O} > V_{CC} + 0.5V$	50	mA
± I _O	DC output source or sink current – bus driver outputs	$-0.5V < V_O < V_{CC} + 0.5V$	35	mA
± I _{GND} , ± I _{CC}	DC V _{CC} or GND current for types with – bus driver outputs		70	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT} P _{TOT} Power dissipation per package - plastic DIL - plastic mini-pack (SO) - plastic shrink mini-pack (SSOP and TSSOP)		for temperature range: -40 to +125°C above +70°C derate linearly with 12 mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

^{1.} The LV is guaranteed to function down to V_{CC} = 1.0V (input levels GND or V_{CC}); DC characteristics are guaranteed from V_{CC} = 1.2V to V_{CC} = 5.5V.

^{1.} Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	-40	°C to +8	5°C	-40°C to	+125°C	UNIT
			MIN	TYP ¹	MAX	MIN	MAX	1
		V _{CC} = 1.2V	0.9			0.9		
V_{IH}	HIGH level Input	V _{CC} = 2.0V	1.4			1.4] _v
VIН	voltage	V _{CC} = 2.7 to 3.6V	2.0			2.0] `
		$V_{CC} = 4.5 \text{ to } 5.5 \text{V}$	0.7 * V _{CC}			0.7 * V _{CC}		
		V _{CC} = 1.2V			0.3		0.3	
V_{IL}	LOW level Input	V _{CC} = 2.0V			0.6		0.6	V
* IL	voltage	V _{CC} = 2.7 to 3.6V			0.8		0.8] `
		$V_{CC} = 4.5 \text{ to } 5.5$			0.3 * V _{CC}		0.3 * V _{CC}	
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$		1.2				
		$V_{CC} = 2.0V$; $V_I = V_{IH}$ or V_{IL} ; $-I_O = 100\mu A$	1.8	2.0		1.8		
V_{OH}	HIGH level output voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	2.5	2.7		2.5		V
	g-,p	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	2.8	3.0		2.8		1
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	4.3	4.5		4.3		1
V	HIGH level output voltage; BUS driver	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 8\text{mA}$	2.40	2.82		2.20		V
V _{OH}	outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 16\text{mA}$	3.60	4.20		3.50		1 ^v
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 100 \mu A$		0				
		$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 100 \mu A$		0	0.2		0.2	1
V_{OL}	LOW level output voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 100 \mu A$		0	0.2		0.2	٧
	Voltago, all outputo	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 100 \mu A$		0	0.2		0.2	1
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	
V	LOW level output voltage; BUS driver	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 8\text{mA}$		0.20	0.40		0.50	V
V_{OL}	outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 16\text{mA}$		0.35	0.55		0.65]
II	Input leakage current	$V_{CC} = 5.5V$; $V_I = V_{CC}$ or GND			1.0		1.0	μА
I _{OZ}	3-State output OFF-state current	V_{CC} = 5.5V; V_I = V_{IH} or V_{IL} ; V_O = V_{CC} or GND			5		10	μΑ
I _{CC}	Quiescent supply current; MSI	$V_{CC} = 5.5V; V_I = V_{CC} \text{ or GND}; I_O = 0$			20.0		160	μА
Δl _{CC}	Additional quiescent supply current	$V_{CC} = 2.7V$ to 3.6V; $V_I = V_{CC} - 0.6V$			500		850	μА

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NOTE:1. All typical values are measured at T_{amb} = 25°C.

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AC CHARACTERISTICS

GND = 0V; $t_r = t_f \le 2.5$ ns; $C_L = 50$ pF; $R_L = 1$ K Ω

			CONDITION			LIMITS			
SYMBOL	PARAMETER	WAVEFORM	CONDITION	_	40 to +85 °	C	-40 to	+125 °C	UNIT
			V _{CC} (V)	MIN	TYP ¹	MAX	MIN	MAX	
			1.2		45	28			
	Propagation delay	l [2.0		15	28		34	
t _{PHL} /t _{PLH}	A_n to B_n ;	Figures 1	2.7		11	19		24	ns
	B _n to A _n	l [3.0 to 3.6		92	16		20	
			4.5 to 5.5		8 ³	11		14	
			1.2		55				
	3-State output enable time	Figures 2	2.0		19	31		39	
t _{PZH} /t _{PZL}	OE to A _n ;		2.7		14	23		29	ns
	OE to B _n	l [3.0 to 3.6		10 ²	18		23	
		l [4.5 to 5.5		8.5 ³	14		18	
			1.2		65				
	3-State output disable time	l [2.0	T	24	32		39	
t _{PHZ} /t _{PLZ}	OE to A _n ; OE to B _n	Figures 2	2.7		18	24		29	ns
	OE to B _n		3.0 to 3.6		14 ²	20		24	
			4.5 to 5.5		11.5 ³	16		19	

NOTES:

- 1. Unless otherwise stated, all typical values are measured at T_{amb} = 25 $^{\circ}$ C
- 2. Typical values are measured at $V_{CC} = 3.3 \text{ V}$.
- 3. Typical values are measured at $V_{CC} = 5.0 \text{ V}$.

AC WAVEFORMS

 V_{M} = 1.5 V at $V_{CC} \geq$ 2.7 V and \leq 3.6 V

 V_{M} = 0.5 V × V_{CC} at V_{CC} < 2.7 V and \geq 4.5 V V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

$$\begin{split} &V_X = V_{OL} + 0.3 \text{ V at } V_{CC} \geq 2.7 \text{ V and } \leq 3.6 \text{ V} \\ &V_X = V_{OL} + 0.1 \times V_{CC} \text{ at } V_{CC} < 2.7 \text{ V and } \geq 4.5 \text{ V} \\ &V_Y = V_{OH} - 0.3 \text{ V at } V_{CC} \geq 2.7 \text{ V and } \leq 3.6 \text{ V} \\ &V_Y = V_{OH} - 0.1 \times V_{CC} \text{ at } V_{CC} < 2.7 \text{ V and } \geq 4.5 \text{ V} \end{split}$$

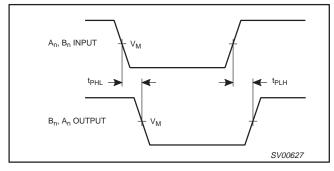


Figure 1. Input (A_n, B_n) to output (B_n, A_n) propagation delays and the output transition times.

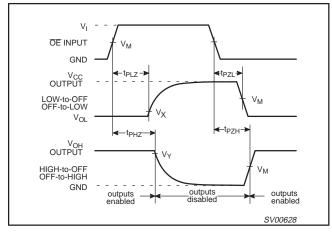


Figure 2. 3-State enable and disable times.

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TEST CIRCUIT

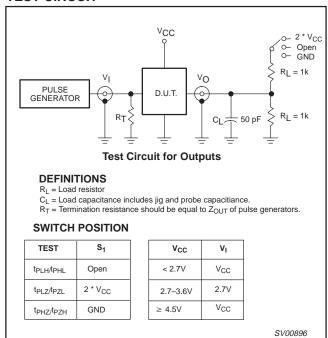


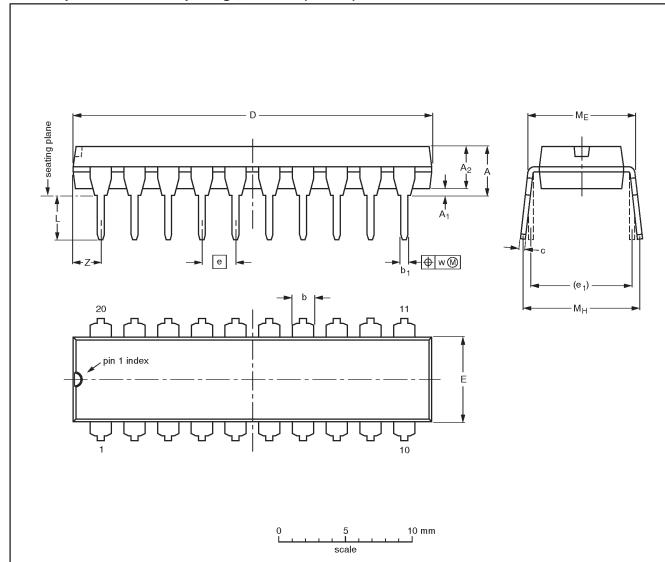
Figure 3. Load circuitry for switching times.

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DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

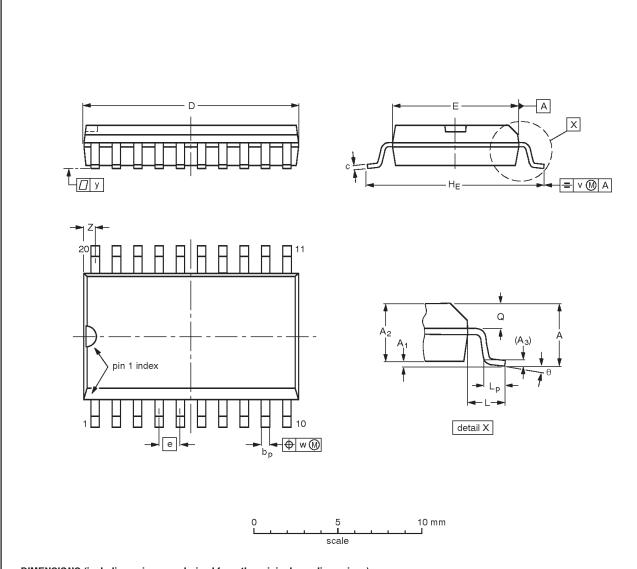
OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT146-1			SC603			92-11-17 95-05-24	

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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bp	O	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	ø	٧	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

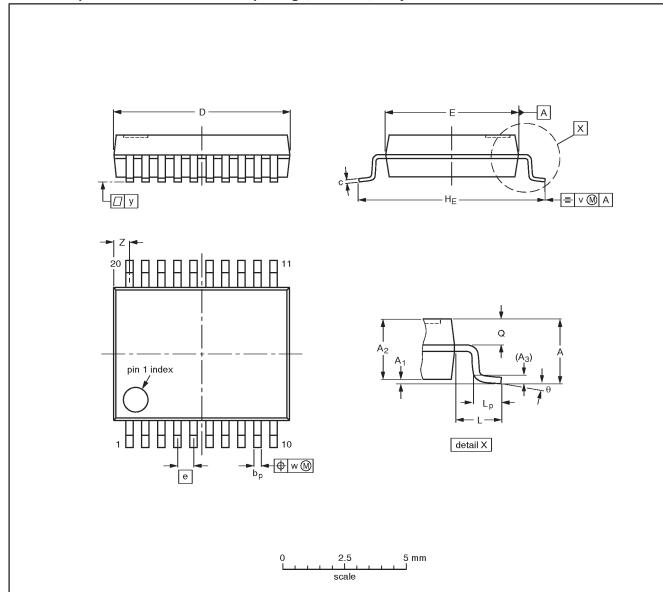
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	IEC JEDEC			PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				-92-11-17 95-01-24	

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SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Ø	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1990E DATE	
SOT339-1		MO-150AE				93-09-08 95-02-04	

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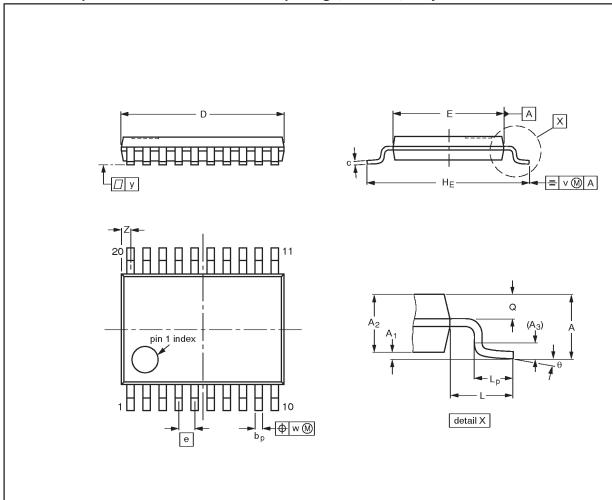
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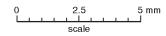
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TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	рb	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Ø	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUEDATE
SOT360-1		MO-153AC				-93-06-16- 95-02-04

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	DEFINITIONS							
Data Sheet Identification	Product Status	Definition						
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.						
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.						
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.						

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